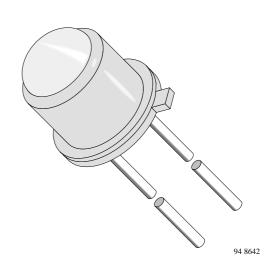
GaAlAs IR Emitting Diode, Hermetically Sealed TO18 Case

Description

TSTA7300 is a high efficiency infrared emitting diode in GaAlAs on GaAlAs technology in a hermetically sealed TO–18 package. Its glass lens provides a high radiant intensity without external optics.

Features

- High radiant power and radiant intensity
- Suitable for pulse operation
- Angle of half intensity $\varphi = \pm 12^{\circ}$
- Peak wavelength $\lambda_p = 875 \text{ nm}$
- High reliability
- Good spectral matching to Si photodetectors



Applications

Radiation source in near infrared range

Absolute Maximum Ratings

 $T_{amb} = 25^{\circ}C$

Parameter	Test Conditions	Symbol	Value	Unit
Reverse Voltage		VR	5	V
Forward Current		IF	100	mA
Peak Forward Current	$t_p/T=0.5, t_p \le 100 \ \mu s$	I _{FM}	200	mA
Surge Forward Current	$t_p \leq 100 \ \mu s$	I _{FSM}	2.5	A
Power Dissipation		P _V	180	mW
	$T_{case} \leq 25 \ ^{\circ}C$	P _V	500	mW
Junction Temperature		Tj	100	°C
Storage Temperature Range		T _{stg}	-55+100	°C
Thermal Resistance Junction/Ambient		R _{thJA}	450	K/W
Thermal Resistance Junction/Case		R _{thJC}	150	K/W

Basic Characteristics

 $T_{amb} = 25^{\circ}C$

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
Forward Voltage	$I_{\rm F} = 100 \text{ mA}, t_{\rm p} \leq 20 \text{ ms}$	V _F		1.4	1.8	V
Breakdown Voltage	$I_R = 100 \ \mu A$	V _(BR)	5			V
Junction Capacitance	$V_{R} = 0$ V, f = 1 MHz, E = 0	Cj		40		pF
Radiant Intensity	$I_{\rm F} = 100 \text{ mA}, t_{\rm p} \leq 20 \text{ ms}$	Ie	10	20		mW/sr
Radiant Power	$I_{\rm F} = 100 \text{ mA}, t_{\rm p} \leq 20 \text{ ms}$	φ _e		10		mW
Temp. Coefficient of ϕ_e	$I_F = 100 \text{ mA}$	ΤK _{φe}		-0.7		%/K
Angle of Half Intensity		φ		±12		deg
Peak Wavelength	$I_F = 100 \text{ mA}$	λρ		875		nm
Spectral Bandwidth	$I_F = 100 \text{ mA}$	Δλ		80		nm
Rise Time	$I_F=1.5A, t_p/T=0.01, t_p \le 10\mu s$	t _r		300		ns
Fall Time	$I_{F}=1.5A, t_{p}/T=0.01, t_{p} \le 10 \mu s$	t _f		300		ns

Typical Characteristics ($T_{amb} = 25^{\circ}C$ unless otherwise specified)

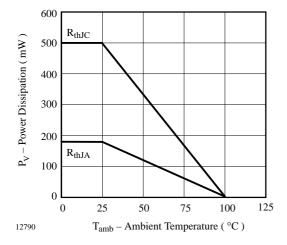


Figure 1. Power Dissipation vs. Ambient Temperature

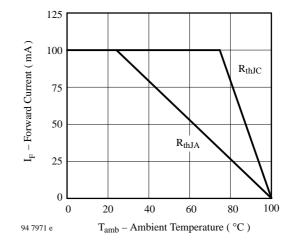


Figure 2. Forward Current vs. Ambient Temperature



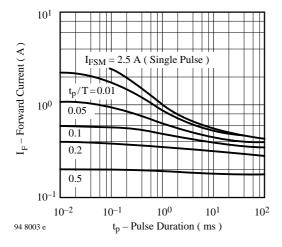
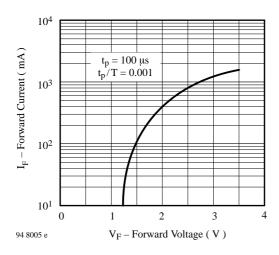
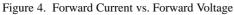


Figure 3. Pulse Forward Current vs. Pulse Duration





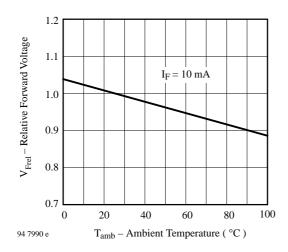


Figure 5. Relative Forward Voltage vs. Ambient Temperature

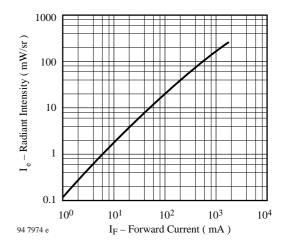


Figure 6. Radiant Intensity vs. Forward Current

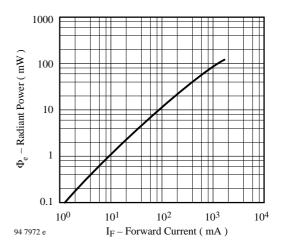


Figure 7. Radiant Power vs. Forward Current

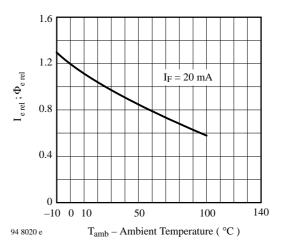


Figure 8. Rel. Radiant Intensity\Power vs. Ambient Temperature

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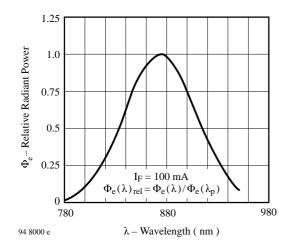
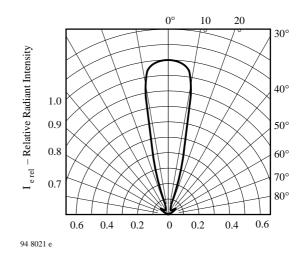


Figure 9. Relative Radiant Power vs. Wavelength



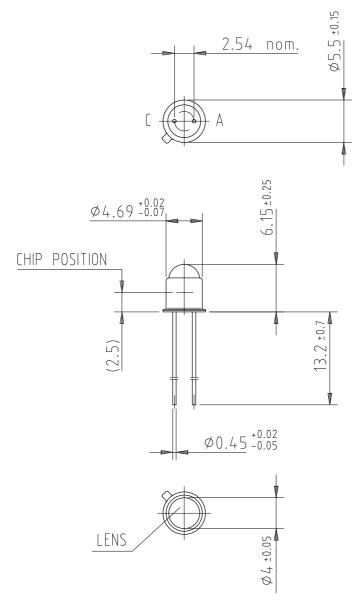
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Figure 10. Relative Radiant Intensity vs. Angular Displacement



Dimensions in mm



96 12179



technical drawings according to DIN specifications

Ozone Depleting Substances Policy Statement

It is the policy of TEMIC TELEFUNKEN microelectronic GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice. Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

TEMIC TELEFUNKEN microelectronic GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany Telephone: 49 (0)7131 67 2831, Fax number: 49 (0)7131 67 2423